

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A circuit board comprising:
an insulating ceramic substrate having two surfaces; and
conductive layers bonded to both surfaces of the insulating ceramic substrate, wherein the
conductive layers comprise at least 99.98% by mass of aluminum, and display an average crystal
grain diameter within a range from 0.5 mm to 5 mm and a standard deviation σ of the crystal grain
diameter less than or equal to ~~of no more than~~ 2 mm.

Claim 2 (currently amended): A circuit board according to claim 1, wherein the conductive
layers comprise rolled materials comprising at least 20 ppm ~~or more~~ of each of Cu, Fe and Si.

Claim 3 (original): A circuit board according to claim 2, wherein the conductive layers are
rolled with a draft of at least 15%.

Claim 4 (currently amended): A circuit board according to claim 1, wherein a surface area
of a crystal with maximum crystal grain diameter within the conductive layers accounts for less than
or equal to ~~no more than~~ 15% of a surface area of the insulating ceramic substrate.

Claim 5 (original): A circuit board according to claim 1, wherein the insulating ceramic
substrate is formed from at least one of Al_2O_3 , AlN and Si_3N_4 .

Claim 6 (currently amended): A circuit board according to claim 1, wherein the conductive
layers are bonded to the a surface of the insulating ceramic substrate using a brazing material, and
the brazing material is one or more materials selected from a group consisting of Al-Si based
materials, Al-Ge based materials, Al-Mn based materials, Al-Cu based materials, Al-Mg based

Claim 10 (original): A power module comprising a circuit board according to claim 1, and a heat radiating plate for supporting the circuit board.

Claim 11 (currently amended): A power module according to claim 10, wherein at least a portion of the conductive layer of the circuit board is bonded to the heat radiating plate using a circuit board brazing material with a lower melting point than the brazing material.